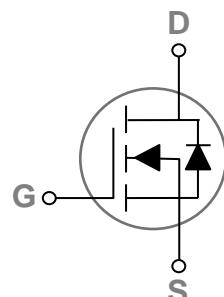


Main Product Characteristics

V_{BDSS}	1000V
$R_{DS(on)}$	5.5Ω
I_D	4A



TO-220



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for DC-DC converter, power management in portable battery, computer, printer, cellular and general purpose applications
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSF04N100T utilizes the latest techniques to achieve high cell density, low on-resistance and high repetitive avalanche rating. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	1000	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current – Continuous ($T_C=25^\circ\text{C}$)	I_D	4	A
Drain Current – Continuous ($T_C=100^\circ\text{C}$)		2.22	A
Drain Current – Pulsed ¹	I_{DM}	16	A
Single Pulse Avalanche Energy ²	E_{AS}	17.8	mJ
Single Pulse Avalanche Current ²	I_{AS}	4	A
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	123	W
Power Dissipation – Derate above 25°C	P_D	0.99	W/ $^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	62	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction to Case	$R_{\theta JC}$	---	1.01	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	1000	---	---	V
Drain-Source Leakage Current	I_{DSS}	$\text{V}_{\text{DS}}=1000\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^\circ\text{C}$	---	---	10	μA
		$\text{V}_{\text{DS}}=800\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=85^\circ\text{C}$	---	---	100	μA
Gate-Source Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 30\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
On Characteristics						
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=2\text{A}$	---	4.2	5.5	Ω
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	2	---	4	V
Forward Transconductance	g_{fs}	$\text{V}_{\text{DS}}=30\text{V}$, $\text{I}_D=2\text{A}$	---	6	---	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3,4}	Q_g	$\text{V}_{\text{DS}}=720\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=4\text{A}$	---	25	---	nC
Gate-Source Charge ^{3,4}	Q_{gs}		---	4.8	---	
Gate-Drain Charge ^{3,4}	Q_{gd}		---	10.2	---	
Turn-On Delay Time ^{3,4}	$\text{T}_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=450\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_G=25\Omega$ $\text{I}_D=4\text{A}$	---	49	---	ns
Rise Time ^{3,4}	T_r		---	38	---	
Turn-Off Delay Time ^{3,4}	$\text{T}_{\text{d}(\text{off})}$		---	146	---	
Fall Time ^{3,4}	T_f		---	50	---	
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=25\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	955	---	pF
Output Capacitance	C_{oss}		---	80	---	
Reverse Transfer Capacitance	C_{rss}		---	13	---	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	4	A
Pulsed Source Current	I_{SM}		---	---	16	A
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=4\text{A}$, $\text{T}_J=25^\circ\text{C}$	---	---	1.5	V
Reverse Recovery Time ³	t_{rr}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=4\text{A}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$ $\text{T}_J=25^\circ\text{C}$	---	487	---	nS
Reverse Recovery Charge ³	Q_{rr}		---	2.8	---	uC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $\text{V}_{\text{DD}}=50\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $L=2.1\text{mH}$, $\text{I}_{\text{AS}}=4\text{A}$, $\text{R}_G=25\Omega$, Starting $\text{T}_J=25^\circ\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristics

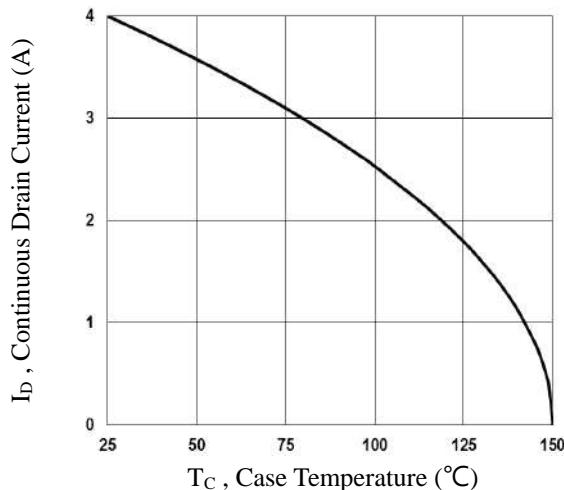


Fig.1 Continuous Drain Current vs. T_c

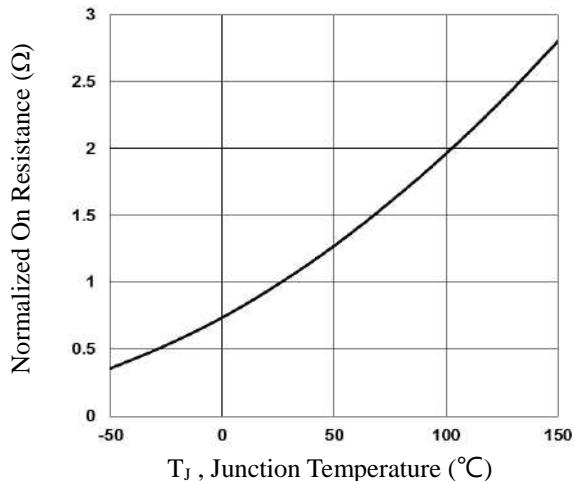


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

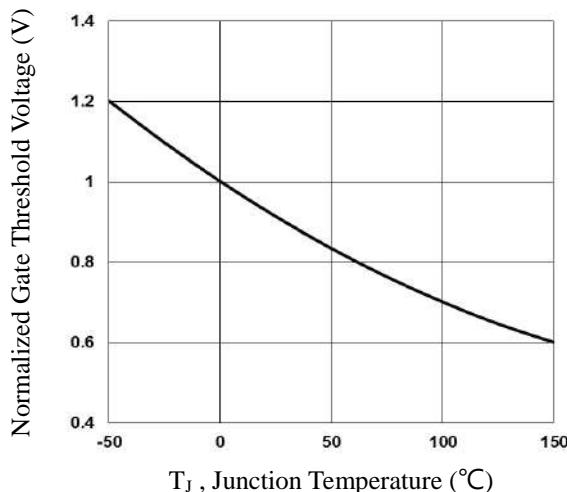


Fig.3 Normalized V_{th} vs. T_J

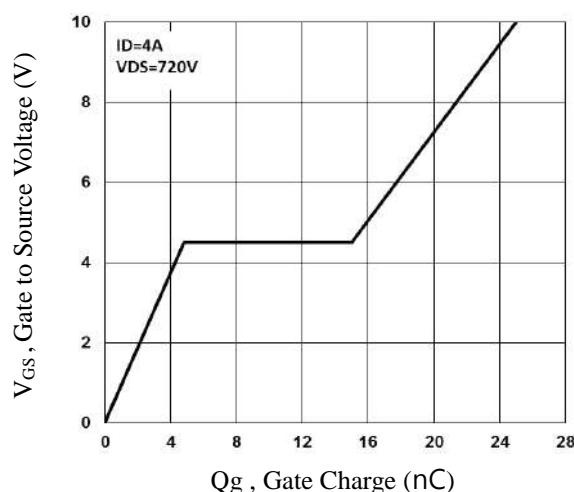


Fig.4 Gate CDcharge Waveform

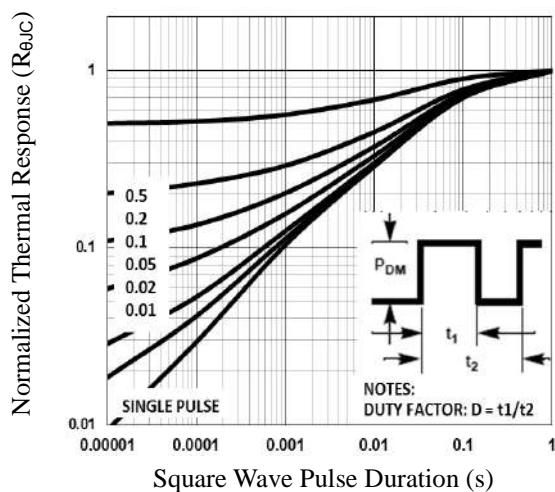


Fig.5 Normalized Transient Impedance

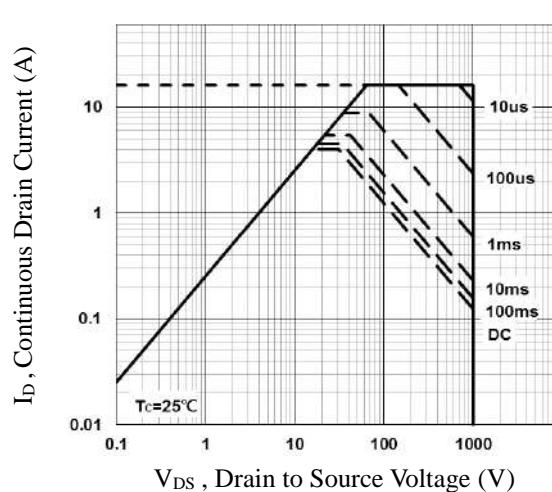


Fig.6 Maximum Safe Operation Area

Typical Electrical and Thermal Characteristics

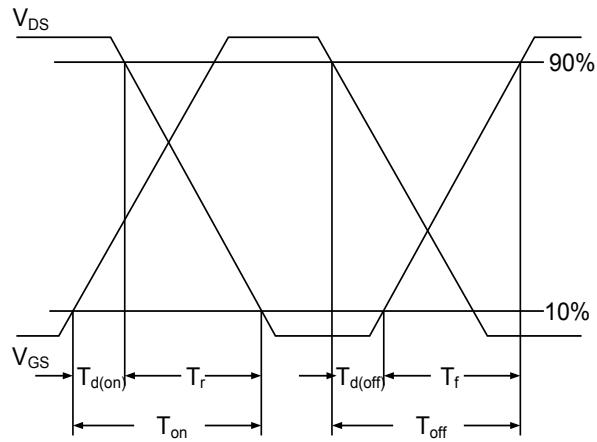


Fig.7 Switching Time Waveform

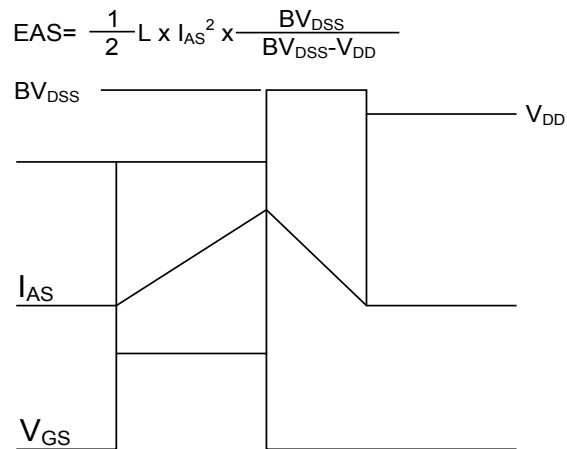
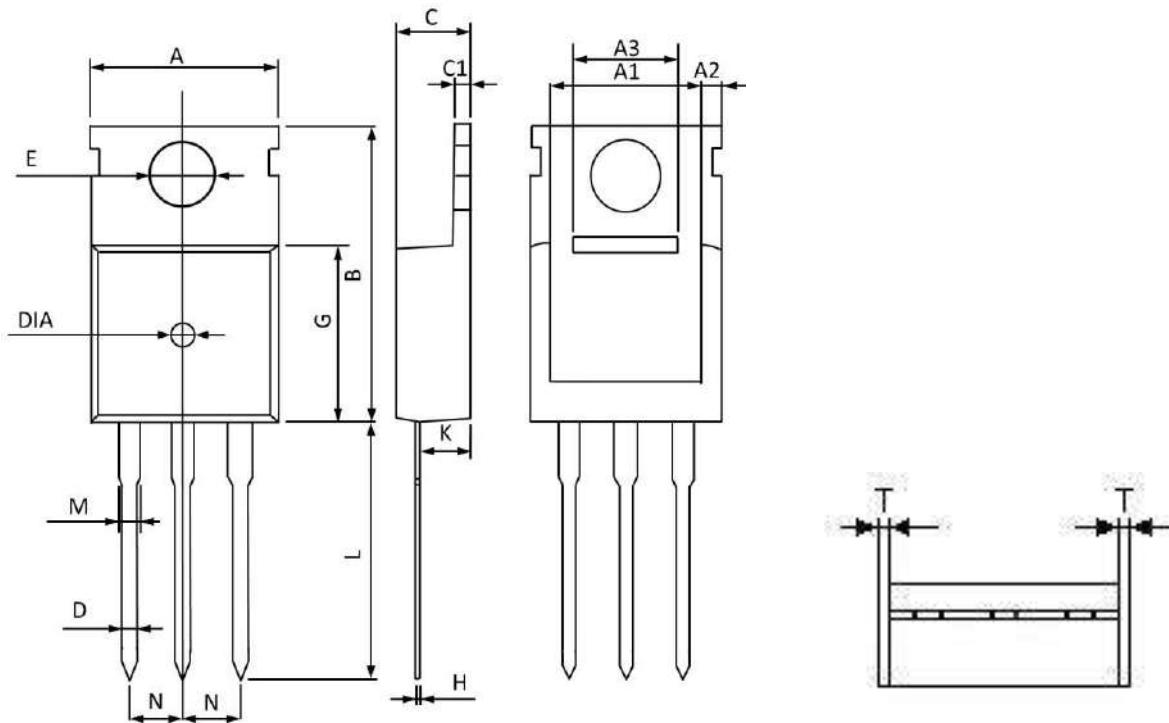


Fig.8 EAS Waveform

Package Outline Dimensions

TO-220



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.700	10.300	0.382	0.405
A1	8.440	8.840	0.333	0.348
A2	1.050	1.250	0.042	0.049
A3	5.100	5.300	0.201	0.208
B	15.400	16.200	0.607	0.637
C	4.280	4.680	0.169	0.184
C1	1.100	1.500	0.044	0.059
D	0.600	1.000	0.024	0.039
E	3.400	3.800	0.134	0.149
G	8.700	9.300	0.343	0.366
H	0.400	0.600	0.016	0.023
K	2.100	2.700	0.083	0.106
L	12.800	13.600	0.504	0.535
M	1.100	1.500	0.044	0.059
N	2.490	2.590	0.099	0.101
T	0.345	0.355	0.014	0.014
DIA	1.450	1.550	0.058	0.061